

Advanced Power MOSFET

SSF9N90A

FEATURES

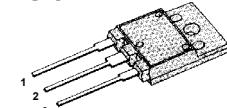
- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 25 μ A (Max.) @ $V_{DS} = 900V$
- Low $R_{DS(ON)}$: 0.938 Ω (Typ.)

$BV_{DSS} = 900 V$

$R_{DS(on)} = 1.4 \Omega$

$I_D = 6 A$

TO-3PF



1.Gate 2. Drain 3. Source

Absolute Maximum Ratings

| Symbol | Characteristic | Value | Units |
|----------------|--|--------------|---------------|
| V_{DSS} | Drain-to-Source Voltage | 900 | V |
| I_D | Continuous Drain Current ($T_C=25^\circ C$) | 6 | A |
| | Continuous Drain Current ($T_C=100^\circ C$) | 3.8 | |
| I_{DM} | Drain Current-Pulsed | 36 | A |
| V_{GS} | Gate-to-Source Voltage | ± 30 | V |
| E_{AS} | Single Pulsed Avalanche Energy | 762 | mJ |
| I_{AR} | Avalanche Current | 6 | A |
| E_{AR} | Repetitive Avalanche Energy | 10 | mJ |
| dv/dt | Peak Diode Recovery dv/dt | 1.5 | V/ns |
| P_D | Total Power Dissipation ($T_C=25^\circ C$) | 100 | W |
| | Linear Derating Factor | 0.8 | W/ $^\circ C$ |
| T_J, T_{STG} | Operating Junction and Storage Temperature Range | - 55 to +150 | $^\circ C$ |
| | Maximum Lead Temp. for Soldering Purposes, 1/8 " from case for 5-seconds | 300 | |

Thermal Resistance

| Symbol | Characteristic | Typ. | Max. | Units |
|-----------------|---------------------|------|------|----------------|
| $R_{\theta JC}$ | Junction-to-Case | -- | 1.25 | $^\circ C / W$ |
| $R_{\theta JA}$ | Junction-to-Ambient | -- | 40 | |

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Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|-------------------------------|---|------|------|------|---------------------|--|
| BV_{DSS} | Drain-Source Breakdown Voltage | 900 | -- | -- | V | $\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$ |
| $\Delta \text{BV}/\Delta T_J$ | Breakdown Voltage Temp. Coeff. | -- | 1.11 | -- | V/ $^\circ\text{C}$ | $\text{I}_D=250\mu\text{A}$ See Fig 7 |
| $\text{V}_{\text{GS(th)}}$ | Gate Threshold Voltage | 2.0 | -- | 3.5 | V | $\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=250\mu\text{A}$ |
| I_{GSS} | Gate-Source Leakage , Forward | -- | -- | 100 | nA | $\text{V}_{\text{GS}}=30\text{V}$ |
| | Gate-Source Leakage , Reverse | -- | -- | -100 | | $\text{V}_{\text{GS}}=-30\text{V}$ |
| I_{DSS} | Drain-to-Source Leakage Current | -- | -- | 25 | μA | $\text{V}_{\text{DS}}=900\text{V}$ |
| | | -- | -- | 250 | | $\text{V}_{\text{DS}}=720\text{V}, \text{T}_C=125^\circ\text{C}$ |
| $\text{R}_{\text{DS(on)}}$ | Static Drain-Source On-State Resistance | -- | -- | 1.4 | Ω | $\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=3\text{A}$ ④* |
| g_{fs} | Forward Transconductance | -- | 5.5 | -- | S | $\text{V}_{\text{DS}}=50\text{V}, \text{I}_D=3\text{A}$ ④ |
| C_{iss} | Input Capacitance | -- | 2760 | 3580 | pF | $\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5 |
| C_{oss} | Output Capacitance | -- | 245 | 290 | | |
| C_{rss} | Reverse Transfer Capacitance | -- | 105 | 125 | | |
| $t_{\text{d(on)}}$ | Turn-On Delay Time | -- | 29 | 70 | ns | $\text{V}_{\text{DD}}=450\text{V}, \text{I}_D=10\text{A}, \text{R}_G=9.6\Omega$ See Fig 13 ④ ⑤ |
| t_r | Rise Time | -- | 54 | 120 | | |
| $t_{\text{d(off)}}$ | Turn-Off Delay Time | -- | 161 | 330 | | |
| t_f | Fall Time | -- | 47 | 105 | | |
| Q_g | Total Gate Charge | -- | 127 | 165 | nC | $\text{V}_{\text{DS}}=720\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{I}_D=10\text{A}$ See Fig 6 & Fig 12 ④ ⑤ |
| Q_{gs} | Gate-Source Charge | -- | 19.2 | -- | | |
| Q_{gd} | Gate-Drain("Miller") Charge | -- | 56.8 | -- | | |

Source-Drain Diode Ratings and Characteristics

| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|------------------------|---------------------------|------|-------|------|-------|--|
| I_s | Continuous Source Current | -- | -- | 6 | A | Integral reverse pn-diode in the MOSFET |
| I_{SM} | Pulsed-Source Current ① | -- | -- | 36 | | |
| V_{SD} | Diode Forward Voltage ④ | -- | -- | 1.4 | V | $\text{T}_J=25^\circ\text{C}, \text{I}_S=6\text{A}, \text{V}_{\text{GS}}=0\text{V}$ |
| t_{rr} | Reverse Recovery Time | -- | 690 | -- | ns | $\text{T}_J=25^\circ\text{C}, \text{I}_F=10\text{A}$ $d\text{I}/dt=100\text{A}/\mu\text{s}$ ④ |
| Q_{rr} | Reverse Recovery Charge | -- | 11.94 | -- | | |

Notes :

- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ② $L=40\text{mH}, \text{I}_{\text{AS}}=6\text{A}, \text{V}_{\text{DD}}=50\text{V}, \text{R}_G=27\Omega$, Starting $\text{T}_J=25^\circ\text{C}$
- ③ $\text{I}_{\text{SD}} \leq 10\text{A}, d\text{I}/dt \leq 190\text{A}/\mu\text{s}, \text{V}_{\text{DD}} \leq \text{BV}_{\text{DSS}}$, Starting $\text{T}_J=25^\circ\text{C}$
- ④ Pulse Test : Pulse Width = $250\mu\text{s}$, Duty Cycle $\leq 2\%$
- ⑤ Essentially Independent of Operating Temperature

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Fig 1. Output Characteristics

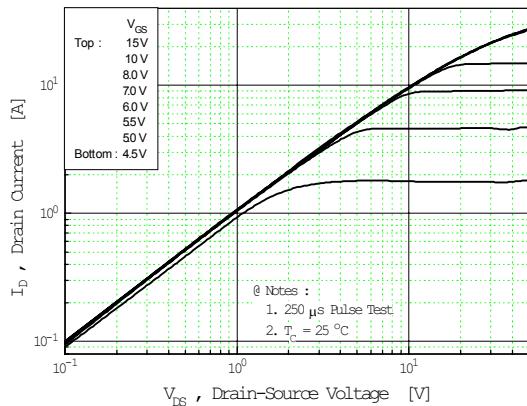


Fig 2. Transfer Characteristics

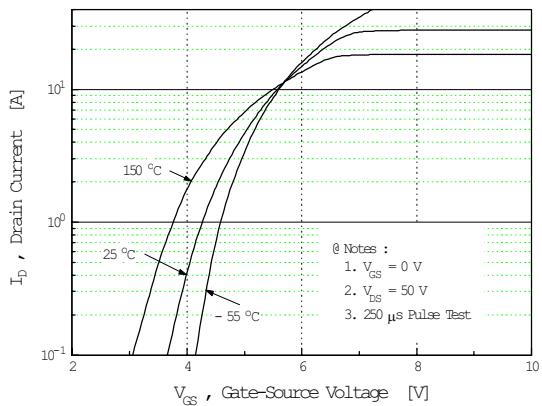


Fig 3. On-Resistance vs. Drain Current

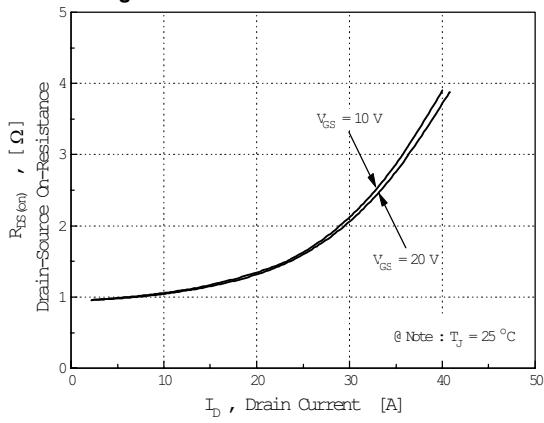


Fig 4. Source-Drain Diode Forward Voltage

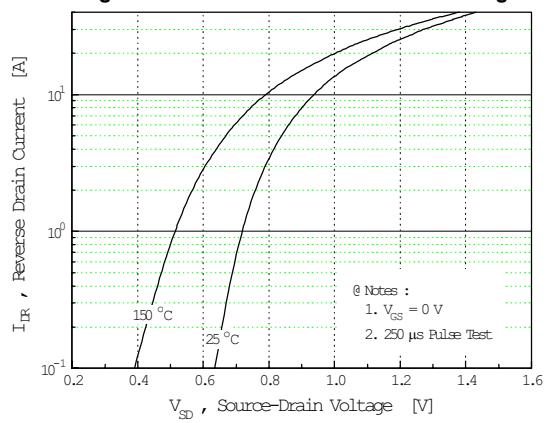


Fig 5. Capacitance vs. Drain-Source Voltage

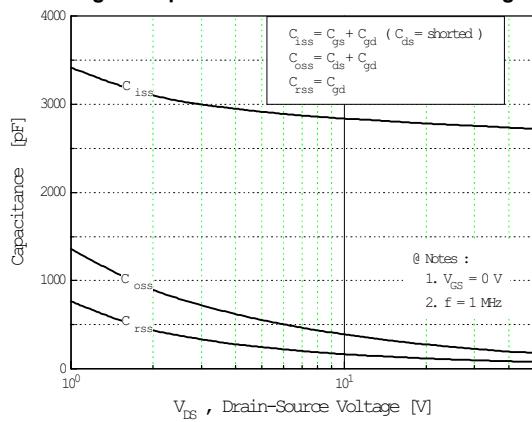
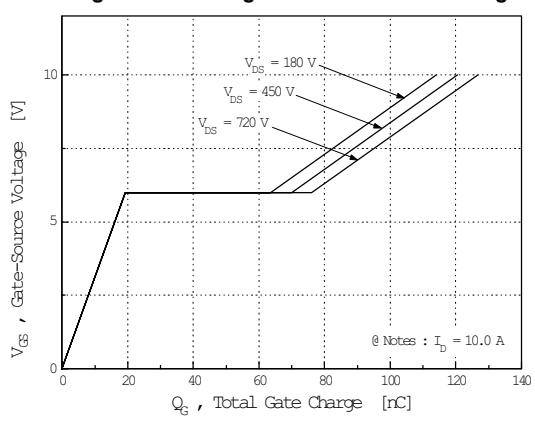
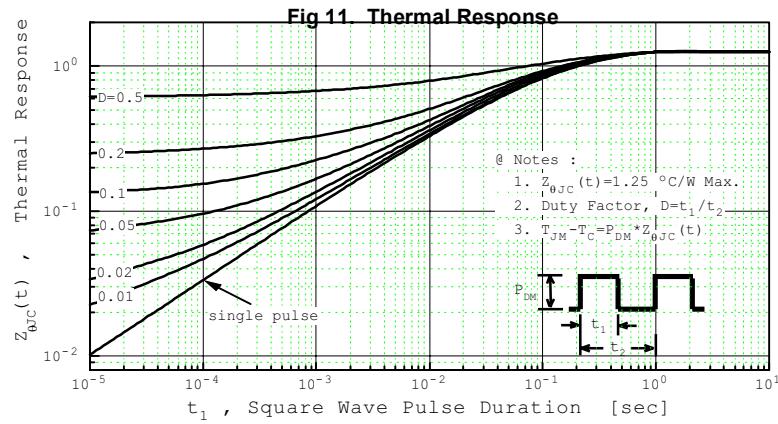
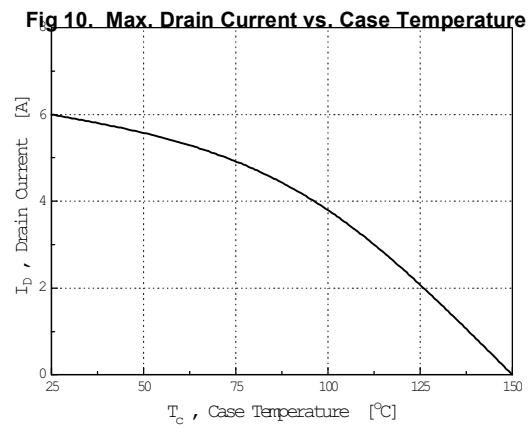
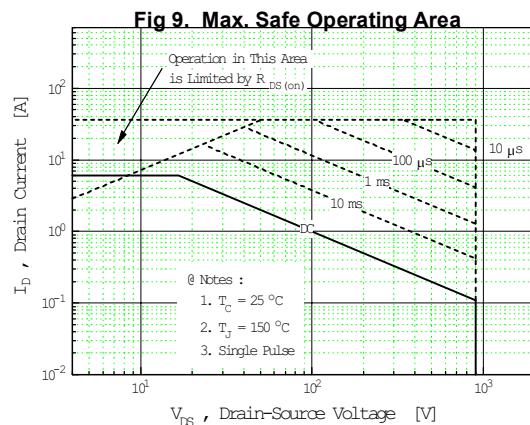
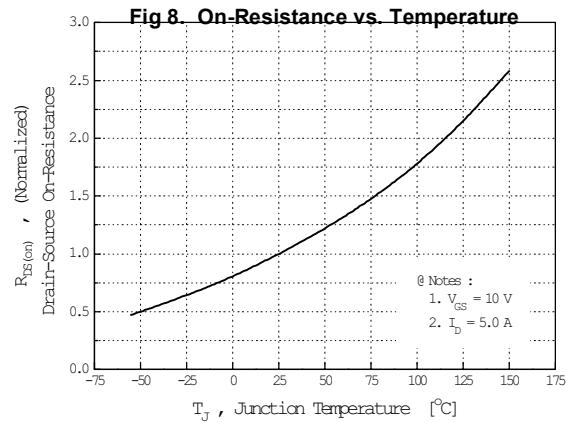
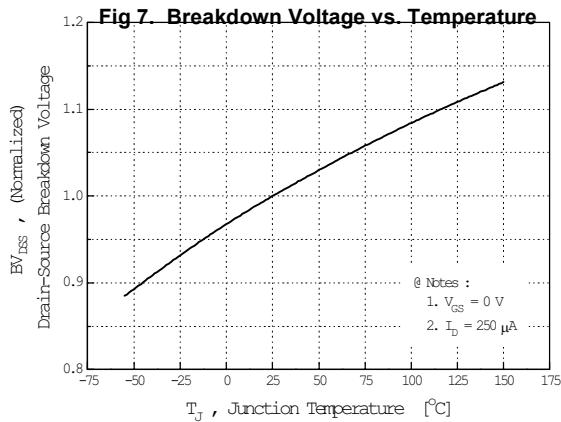


Fig 6. Gate Charge vs. Gate-Source Voltage



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Fig 12. Gate Charge Test Circuit & Waveform

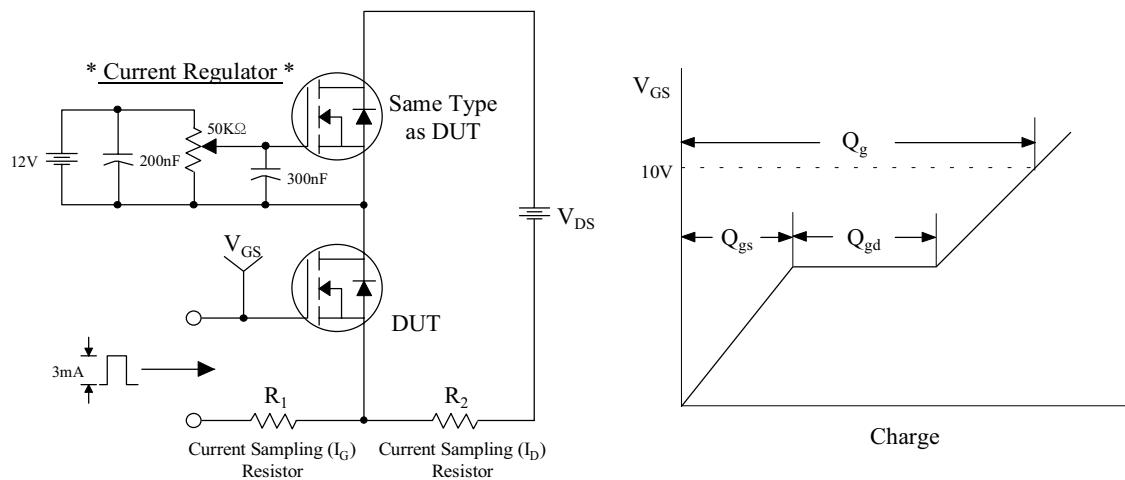


Fig 13. Resistive Switching Test Circuit & Waveforms

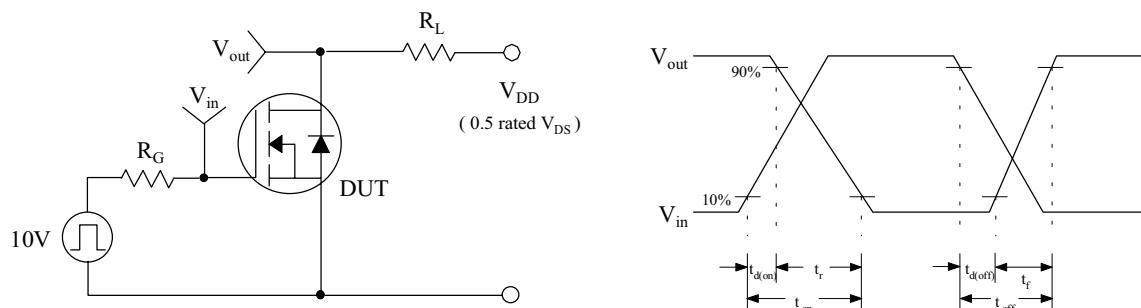
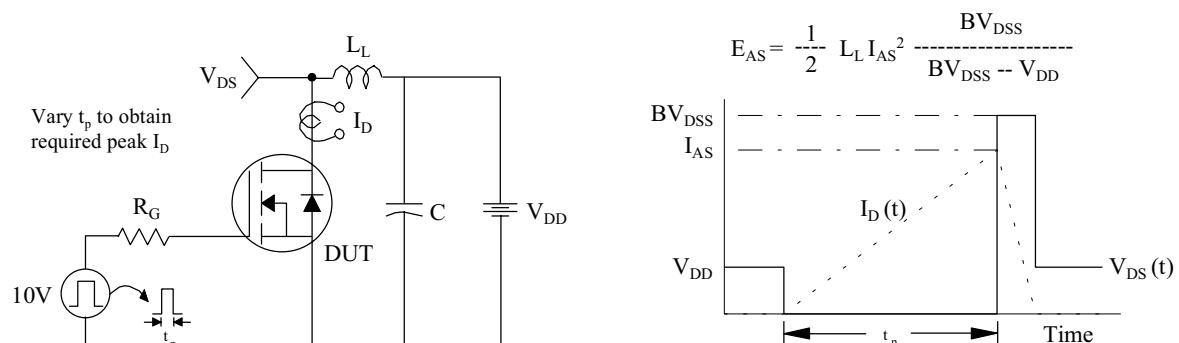


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

